



HIGH-SIDE AND LOW-SIDE GATE DRIVER IN SO-14 (Type TH)

Description

The DGD21904 is a high voltage / high speed gate driver capable of driving N-Channel MOSFETs and IGBTs in a half bridge configuration. High voltage processing techniques enable the DGD21904's high-side to switch to 600V in a bootstrap operation under high dV/dt conditions.

The DGD21904 logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) for easy interfacing with controlling devices. The driver outputs feature high pulse current buffers designed for minimum driver cross conduction.

The DGD21904 is available in SO-14 (Type TH) package. The operating temperature extends from -40°C to +125°C.

Applications

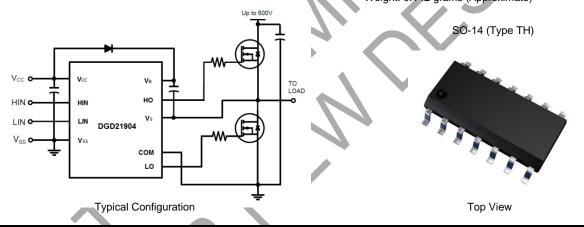
- **DC-DC** Converters
- **DC-AC Inverters**
- **AC-DC Power Supplies**
- Motor Controls
- **Class D Power Amplifiers**

Features

- Floating High-side Driver in Bootstrap Operation to 600V •
- Drives Two N-Channel MOSFETs or IGBTs in a Half Bridge Configuation
- Output Drivers Capable of 4.5A/4.5A Typ Sink/Source
- Logic Input (HIN and LIN) 3.3V Capability
- Schmitt Triggered Logic Inputs with Internal Pull Down
- Undervoltage Lockout for High and Low-side Drivers
- Extended Temperature Range: -40°C to +125°C
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony free. "Green" Device (Note 3)

Mechanical Data

- Case: SO-14 (Type TH)
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (3)
 - Weight: 0.142 grams (Approximate)



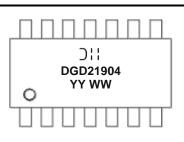
Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
DGD21904S14-13	DGD21904	13	16	2,500

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. Notes:

- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information

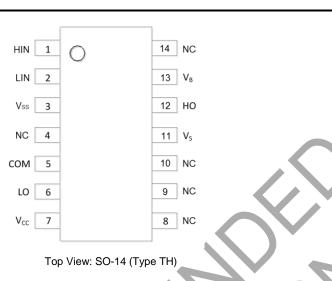


= Manufacturer's Marking וור DGD21904 = Product Type Marking Code = Year (ex: 17 = 2017) YY WW

= Week (01 to 53)



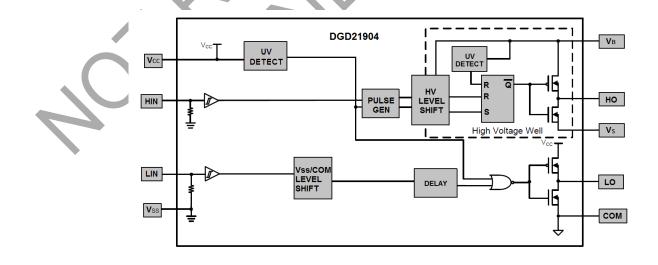
Pin Diagrams



Pin Descriptions

Pin Number	Pin Name	Function
1	HIN	Logic input for high-side gate driver output, in phase with HO
2	LIN	Logic input for low-side gate driver output, in phase with LO
3	Vss	Logic ground
4, 8, 9, 10, 14	NC	No connection (No Internal Connection)
5	COM	Low-side and logic return
6	LO	Low-side gate drive output
7	V _{CC}	Low-side and logic fixed supply
11	Vs	High-side floating supply return
12	HO	High-side gate drive output
13	VB	High-side floating supply

Functional Block Diagram





Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
High-side Floating Supply Voltage	VB	-0.3 to +624	V
High-side Floating Supply Offset Voltage	Vs	V _B -24 to V _B +0.3	V
Logic Supply Offset Voltage	V _{SS}	V _{CC} -24 to V _{CC} +0.3	V
High-side Floating Output Voltage	V _{HO}	V _S -0.3 to V _B +0.3	V
Offset Supply Voltage Transient	dVs / dt	50	V/ns
Low-side and Logic Fixed Supply Voltage	V _{CC}	-0.3 to +24	V
Low-side Output Voltage	V _{LO}	-0.3 to V _{CC} +0.3	V
Logic Input Voltage (HIN and LIN)	V _{IN}	-0.3 to V _{CC} +0.3	V

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Symbol	Value	Unit
PD	0.862	W
R _{0JA}	145	°C/W
TJ	+150	
TL	+300	°C
T _{STG}	-55 to +150	
	PD Reja Tj TL	PD 0.862 R _{0JA} 145 TJ +150 TL +300

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

Parameter	Symbol	Min	Max	Unit
High Side Floating Supply Absolute Voltage	VB	V _S + 10	V _S + 20	V
High Side Floating Supply offset voltage	Vs	(Note 6)	600	V
Logic Ground	V _{SS}	-5	5	V
High Side Floating Output Voltage	V _{HO}	Vs	VB	V
Low Side Fixed Supply Voltage	V _{CC}	10	20	V
Low Side Output Voltage	VLO	0	V _{CC}	V
Logic Input Voltage (HIN and LIN)	VIN	0	5	V
Ambient Temperature	TA	-40	+125	°C

Note: 6. Logic operation for V_S of -5V to +600V. Logic state held for V_S of -5V to - V_{BS} .





DC Electrical Characteristics (V_{BIAS} (V_{CC} , V_{BS}) = 15V, $@T_A$ = +25°C, unless otherwise specified.) (Note 7)

Parameter	Symbol	Min	Тур	Max	Unit	Conditions
Logic "1" Input Voltage	VIH	2.5	_	_	V	$V_{CC} = 10V$ to 20V
Logic "0" Input Voltage	VIL	—	—	0.8	V	$V_{CC} = 10V$ to 20V
High Level Output Voltage, V _{BIAS} - V _O	Voh	—	—	0.1	V	$I_0 = 0 m A$
Low Level Output Voltage, V _O	V _{OL}	—	—	0.035	V	$I_0 = 0 m A$
Offset Supply Leakage Current	I _{LK}	—	—	50	μA	$V_{B} = V_{S} = 600V$
Quiescent V _{BS} Supply Current	I _{BSQ}	—	45	80	μA	$V_{IN} = 0V \text{ or } 5V$
Quiescent V _{CC} Supply Current	ICCQ	—	75	200	μA	$V_{IN} = 0V \text{ or } 5V$
Logic "1" Input Bias Current	I _{IN+}	—	25	50	μA	V _{IN} = 5V
Logic "0" Input Bias Current	I _{IN-}	—	1.0	2.0	μA	$V_{IN} = 0V$
V _{BS} Supply Undervoltage Positive Going Threshold	V _{BSUV+}	7.6	8.4	9.8	V	
V _{BS} Supply Undervoltage Negative Going Threshold	VBSUV-	6.9	7.8	9.0	V	
V _{CC} Supply Undervoltage Positive Going Threshold	V _{CCUV+}	7.6	8.4	9.8	V	—
V _{CC} Supply Undervoltage Negative Going Threshold	V _{CCUV} -	6.9	7.8	9.0	V	—
Versiond Vers Lindon voltage Hypetorogia	V _{CCUVH}	—	0.6		V	_
V _{CC} and V _{BS} Undervoltage Hysteresis	V _{BSUVH}	—	0.6		V	_
Output High Short Circuit Pulsed Current	I _{O+}	3.5	4.5	—	А	$V_0 = 0V$, PW $\leq 10ms$
Output Low Short Circuit Pulsed Current	I _{O-}	3.5	4.5		A	Vo = 15V, PW ≤ 10ms

Note: 7. The V_{IN} and I_{IN} parameters are applicable to the two logic pins; HIN and LIN The V₀ and I₀ parameters are applicable to the respective output pins: HO and LO.

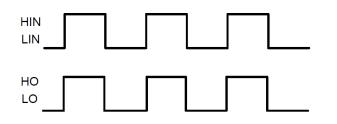
AC Electrical Characteristics (V_{BIAS} (V_{CC}, V_{BS}) = 15V, C_L = 1000pF, @T_A = +25°C, unless otherwise specified.)

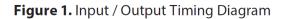
Parameter		Symbol	Min	Тур	Max	Unit	Conditions
Turn-on Propagation Delay		ton		140	200	ns	$V_S = 0V$
Turn-off Propagation Delay		tOFF		140	200	ns	$V_{\rm S} = 0V$
Delay Matching, HO & LO Turn On/Off		tом		-	50	ns	—
Turn-on Rise Time		t _R	L	25	50	ns	$V_{\rm S} = 0V$
Turn-off Fall Time		t _F		20	45	ns	$V_{S} = 0V$





Timing Waveforms





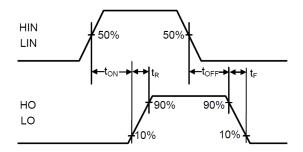


Figure 2. Switching Time Waveform Definitions

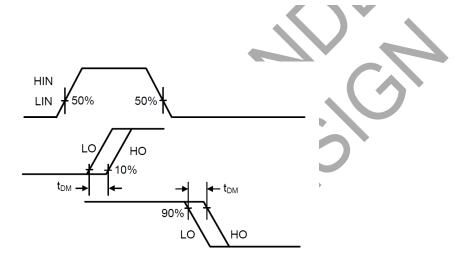


Figure 3. Delay Matching Waveform Definitions



Typical Performance Characteristics (@T_A = +25°C, unless otherwise specified.)

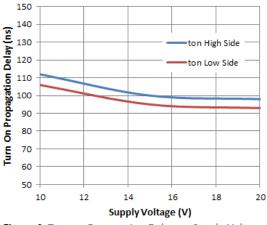


Figure 4. Turn-on Propagation Delay vs. Supply Voltage

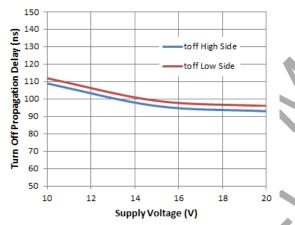
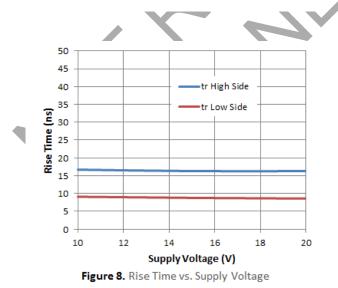


Figure 6. Turn-off Propagation Delay vs. Supply Voltage



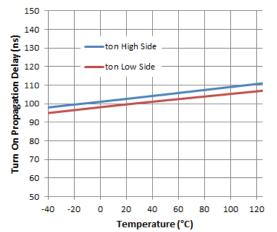


Figure 5. Turn-on Propagation Delay vs. Temperature

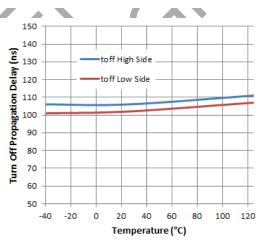


Figure 7. Turn-off Propagation Delay vs. Temperature

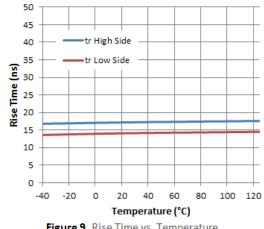
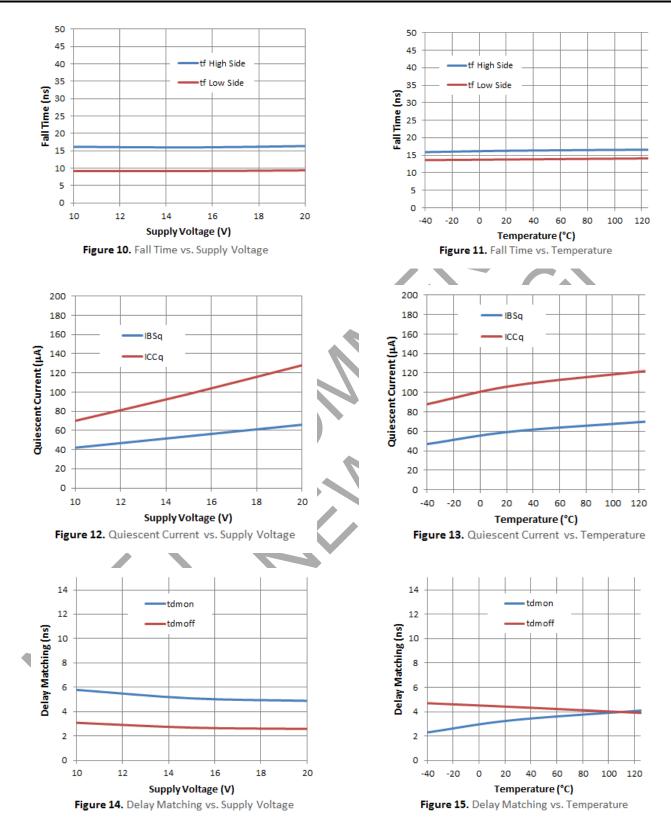


Figure 9. Rise Time vs. Temperature



Typical Performance Characteristics (Cont.)





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Typical Performance Characteristics (Cont.)

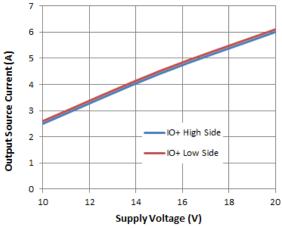


Figure 16. Output Source Current vs. Supply Voltage

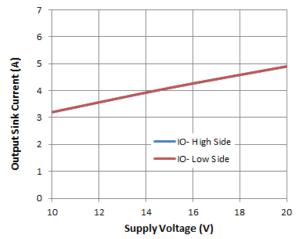


Figure 18. Output Sink Current vs. Supply Voltage

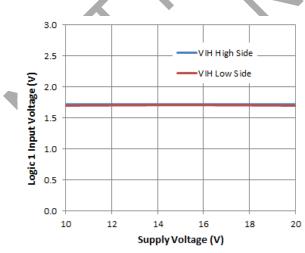
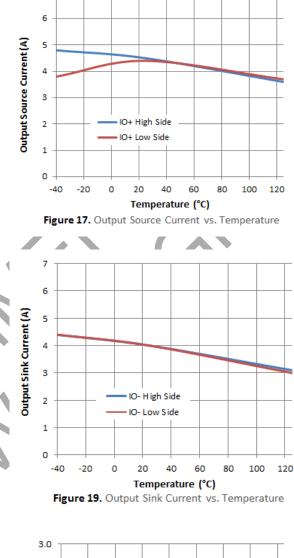


Figure 20. Logic 1 Input Voltage vs. Supply Voltage



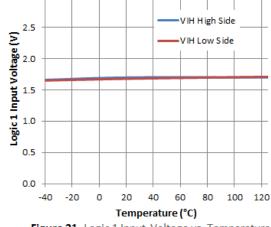
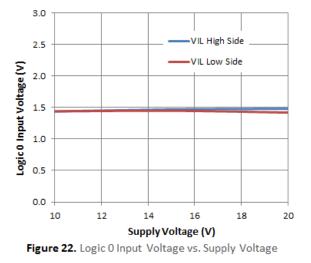
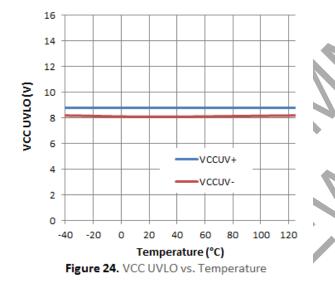


Figure 21. Logic 1 Input Voltage vs. Temperature



Typical Performance Characteristics (Cont.)





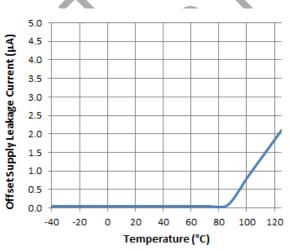


Figure 26. Offset Supply Leakage Current vs. Temperature

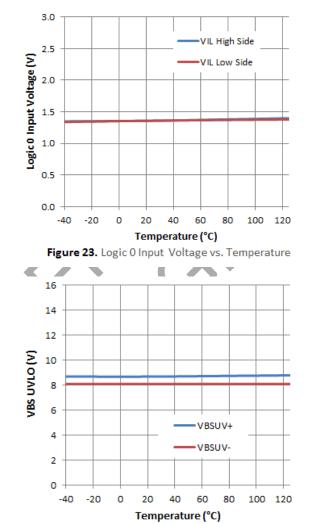


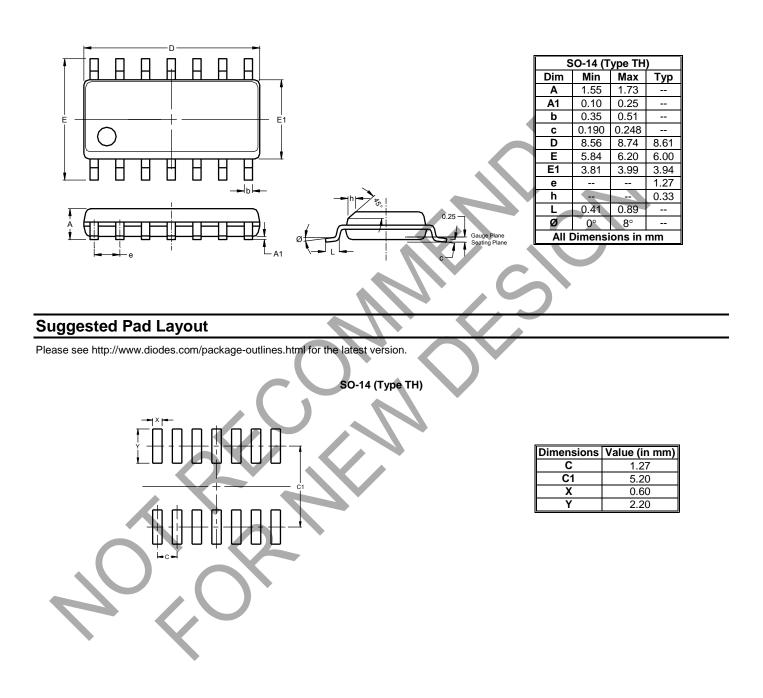
Figure 25. VBS UVLO vs. Temperature



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SO-14 (Type TH)



Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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